

REMARKS

The Title of the application has been changed to "Method of Preventing Diffusion of Copper Through a Tantalum-comprising Barrier Layer" in order to more accurately reflect the presently claimed subject matter.

Amendments have been made to the specification for the purpose of correcting informalities present in the originally filed specification.

The Abstract has been amended so as to be 150 words or less in length, in accordance with the PTO's present requirement.

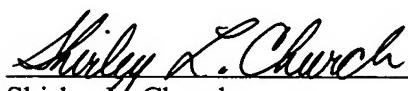
Claims 1 - 30, which have been allowed in the parent application (U.S. Application Serial No. 09/886,439), have been cancelled herein.

New Claims 31 - 34 have been added to claim subject matter previously disclosed but not claimed. Support for the new claims is found in the application as originally filed at Page 10, lines 1 - 7.

Applicants contend that the presently pending claims are in condition for allowance, and the Examiner is respectfully requested to enter the requested amendment and to pass the application to allowance.

The Examiner is invited to contact applicants' attorney with any questions or suggestions, at the telephone number provided below.

Respectfully submitted,


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